

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An organic positive temperature coefficient thermistor device comprising a pair of electrodes disposed so as to oppose each other, and a thermistor body having a positive resistance-temperature characteristic disposed between the electrodes, wherein the thermistor body consists of a cured product of a mixture containing ~~an epoxy resin including a flexible epoxy resin, a curing agent, and an electrically conductive particle~~ a curing agent, an electrically conductive particle and an epoxy resin including a flexible epoxy resin selected from at least one of:

an epoxy resin having a linear structure that consists of any divalent organic groups expressed by the following formulas (iii) or (v) combined to at least two glycidyl ether groups:

- (CH₂)_n - (iii), wherein n in the formulas (iii) is an integer between 1 and 20; and

-CH₂C(C₂H₅)(CH₃)CH₂ - (v);

a rubber-modified epoxy resin, wherein fine particles of liquid rubber of polybutylene (BR) or butadiene/acrylonitrile (NBR) having a carboxyl group, hydroxyl group or epoxy group at a terminal, or polybutadiene (PBR) having a carboxyl group or hydroxyl group at a terminal, are dispersed;

an epoxy resin containing fine particles of silicone rubber having a reactive group at a terminal;

an epoxy resin having a siloxane bond (-Si-O-Si- bond) within a molecule;

a urethane-modified epoxy resin obtained when a urethane prepolymer obtained by a reaction between polyether polyol and polyisocyanate is reacted with an epoxy resin having a hydroxyl group within a molecule;

an epoxidized polyolefin;

a polythiol-based epoxy resin; and

a polyol-based epoxy resin.

2. (Original) An organic positive temperature coefficient thermistor device according to claim 1, wherein the epoxy resin includes 3 to 100 % by mass of the flexible epoxy resin based on the total mass of the epoxy resin.

3. (Original) An organic positive temperature coefficient thermistor device comprising a pair of electrodes disposed so as to oppose each other, and a thermistor body having a positive resistance-temperature characteristic disposed between the electrodes, wherein the thermistor body consists of a cured product of a mixture containing a flexible epoxy resin having a bending elasticity of 2700 MPa or less and an electrically conductive particle.

4. (Previously Presented) An organic positive temperature coefficient thermistor device according to claim 1, wherein the conductive particle has a surface provided with a protrusion.

5. (Previously Presented) An organic positive temperature coefficient thermistor device according to claim 2, wherein the conductive particle has a surface provided with a protrusion.

6. (Previously Presented) An organic positive temperature coefficient thermistor device according to claim 3, wherein the conductive particle has a surface provided with a protrusion.